SLG47115V GreenPAK DIP Adapter

This user guide is intended to familiarize new users with the SLG47115V GreenPAK DIP Adapter. It consists of the description of the board, lists its features, shows top and bottom views, as well as the board schematic.

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1. Description

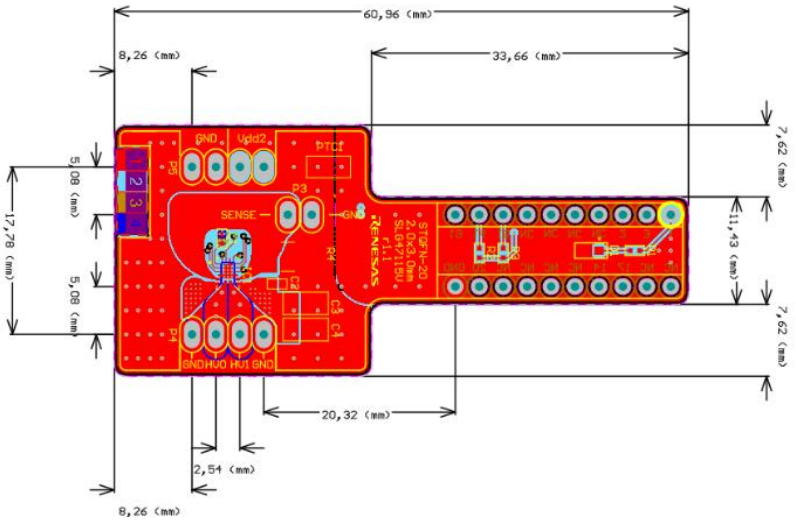
The SLG47115 DIP Adapter is a small PCB that lets you adapt STQFN packages into a DIP footprint. This board can speed up your design prototyping and testing. This small board 0.90x2.20 inch uses 20 pins DIP footprint with 0.3 inch width. You can also use this adapter for prototyping by making STQFN package compatible with solder free breadboards.

2. Features

- Low cost
- Simplifies prototyping of SMT IC's
- Four high voltage high current output GPOs
- Current up to 2 A per HV GPO
- Current sensing resistors
- Variable current sensing configurations
- Optional V_{DD} LED indicator
- Decoupling capacitor included
- Screw terminals for high voltage and high current lines
- Optional I^2C pull-up resistors

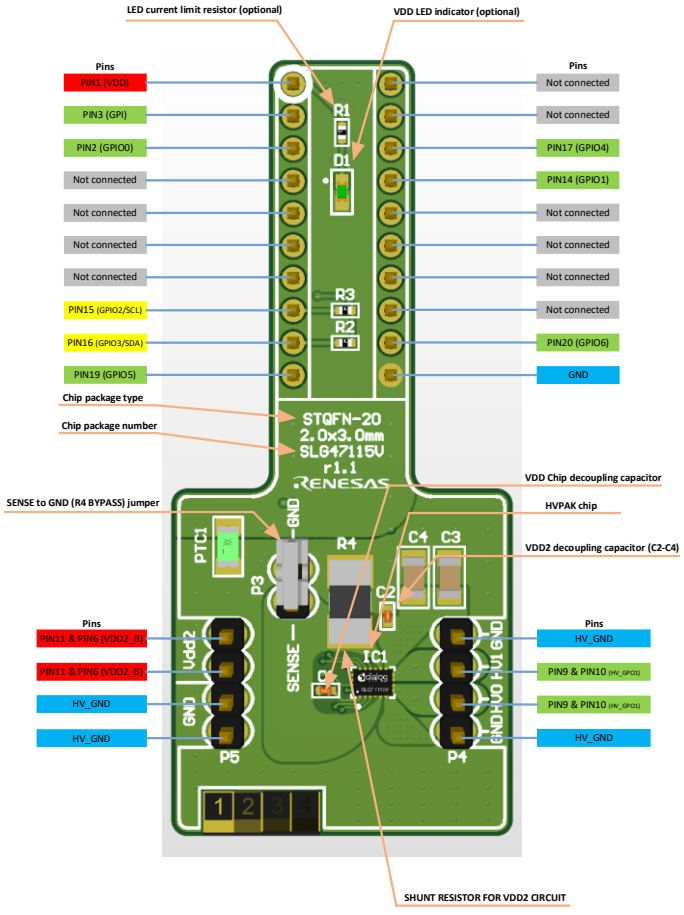
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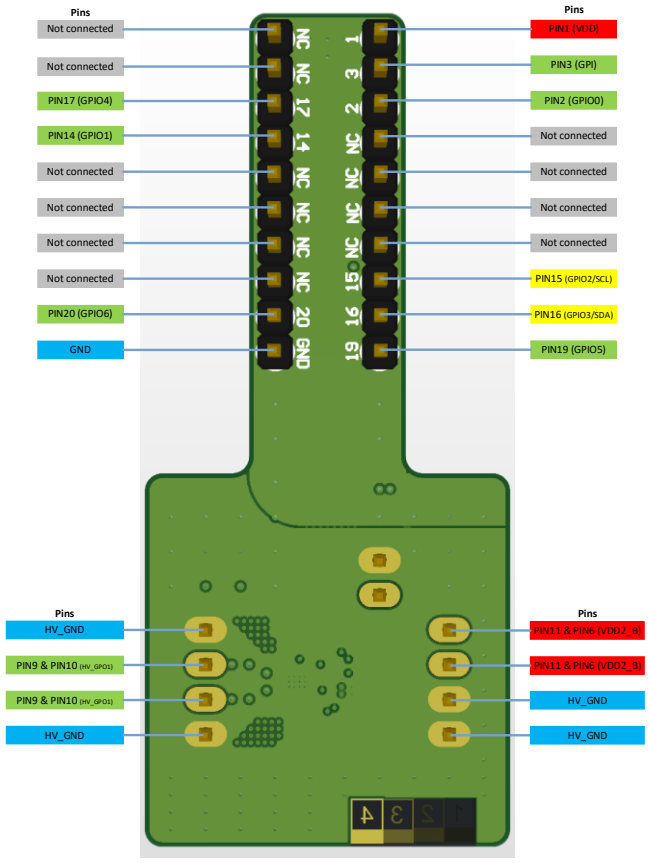


Note 1: All sizes in millimeters (mm).

3. Top View

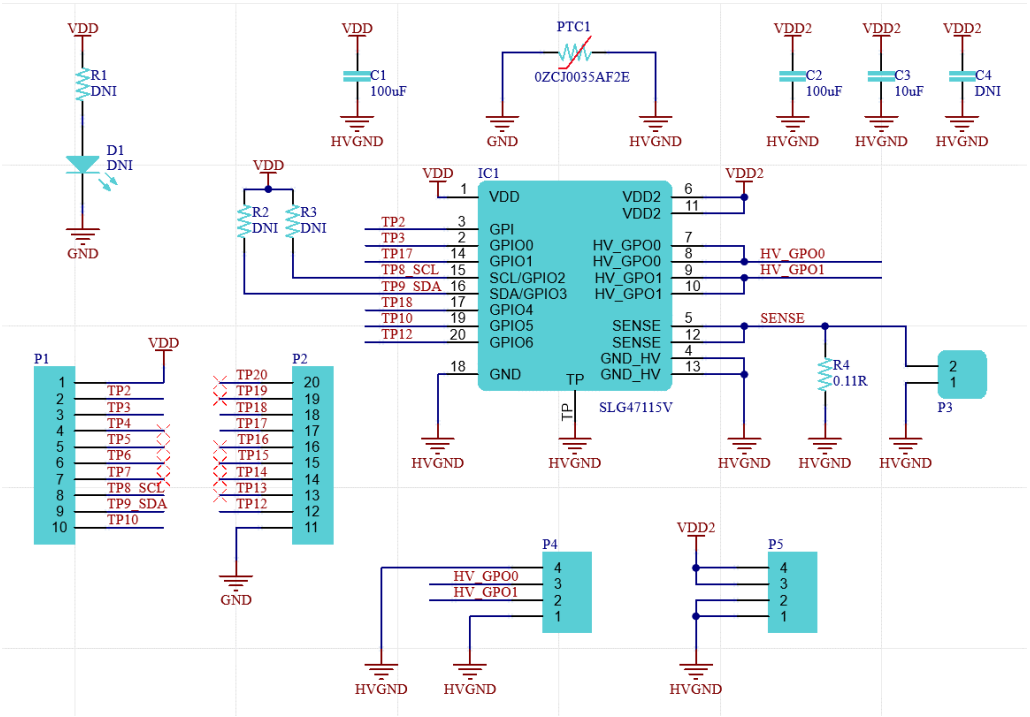


4. Bottom View



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5. Board Schematic



6. Revision History

Revision	Date	Description
1.00	May 12, 2022	Initial release.

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